Frontiers in Nanosciences

Marina Pivetta

Stefano Rusponi

Laboratory of Nanostructures at Surfaces IPHYS

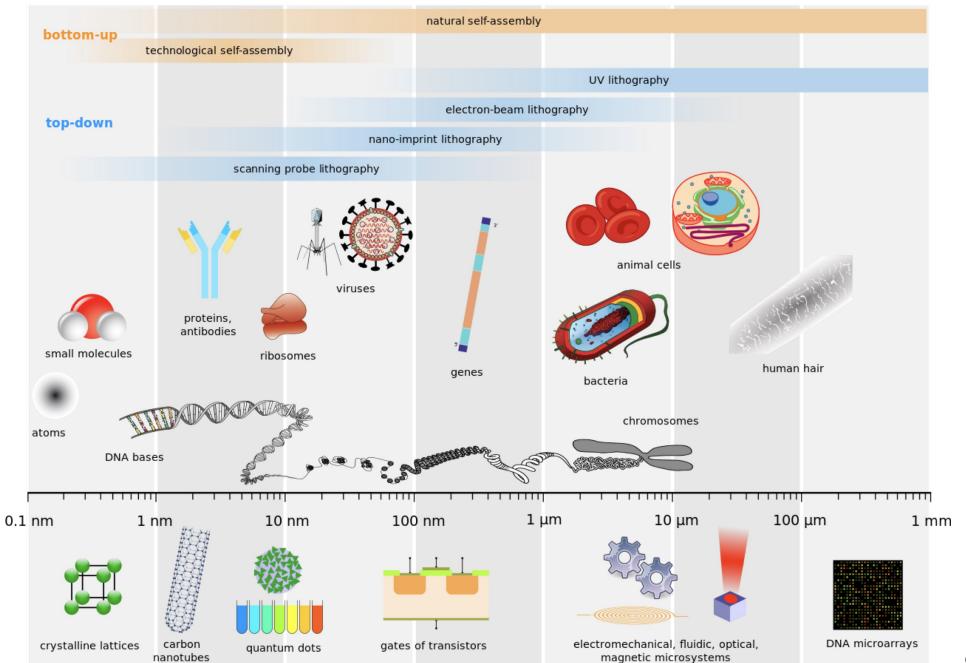
Fall 2024

Frontiers in Nanosciences

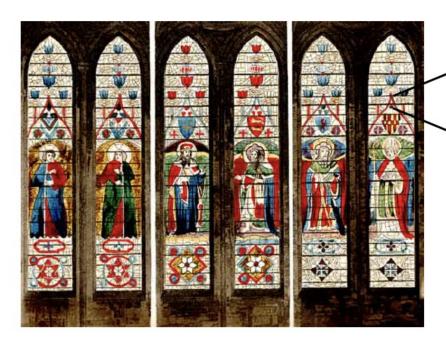
Program

Introduction to the concepts of nanoscale science	week 1	
From atoms to bulk: electronic states	week 2	
Imaging and manipulation at the atomic scale: scanning probe techniques	weeks 3-4	
Magnetism at the nanoscale: magnetic data storage concepts (hard disk drive)	weeks 5-7	Rusponi
Spin transport: spin valve, GMR and TMR effects	week 8	Rusponi
Making the nanostructures: top-down and bottom-up approaches		
Electron transport in low-dimensional systems		
Characterization of structural and electronic properties, for example by TEM, XPS, XAS		
2D materials		

Nanoscale

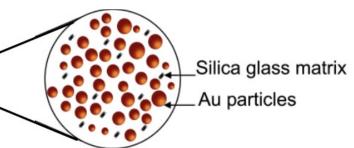


(Quantum) Size Effects





Medieval Nanotechnology





Lycurgus Cup
Au and Ag particles, 70 nm



Michael Faraday discovered in **1851** that the colors of ruby gold were due to its finely divided state





Original Au colloids still on display at the Royal Institution

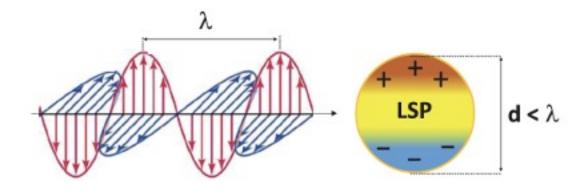
Plasmons: collective oscillations of free electrons in metals

Light: limited penetration depth (skin depth)

→ excitation of Surface Plasmon Resonances

Metallic nanoparticles (size comparable to the metal skin depth)

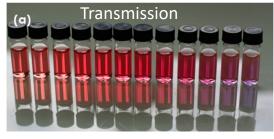
→ Localized Surface Plasmon Resonances



Au nanoparticles, size 20 - 100 nm

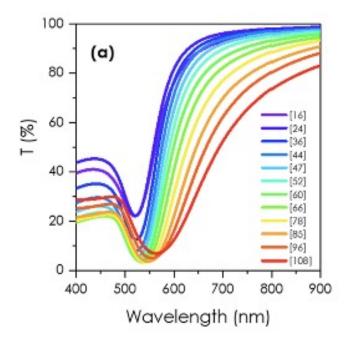
the plasmon resonance is in the 500 - 600 nm range (green) → they appear red / reddish in transmission

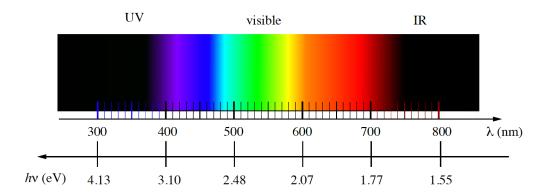
A complete explanation of the plasmonic colours of gold nanoparticles and of the bichromatic effect, J. Mater. Chem. C **11**, 15824 (2023)





 Au_{16} to Au_{108}







When scattering dominates the LSP resonance color is observed

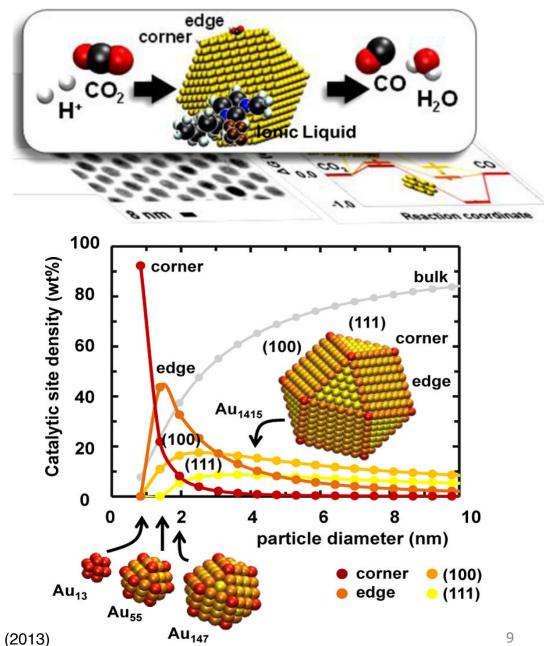
When absorption dominates, the complementary color is seen

Modern applications:

organic photovoltaics sensor probes staining therapeutic agents drug delivery electronic conductors catalysis

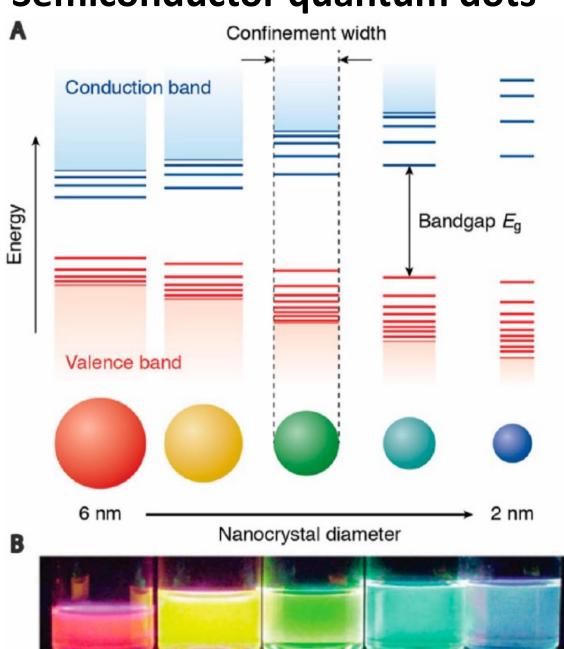
. . .

The optical and electronic properties of gold nanoparticles are tunable by changing the size, shape, surface chemistry, or aggregation state.



10.1021/ja409445p J. Am. Chem. Soc. **135**, 16833 (2013)

Semiconductor quantum dots



CdSe Nanocrystals

10.1021/acs.jpclett.7b01640 J. Phys. Chem. Lett. **8**, 4077 (2017) Nothing tends so much to the advancement of knowledge as the application of a new instrument

Sir Humphry Davy (1778 - 1829)

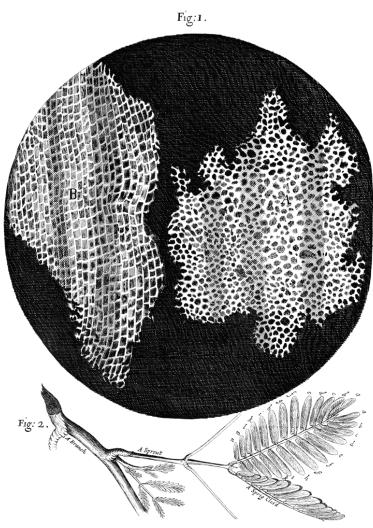


A Very Short History of Microscopy

Optical microscopes

Schem:XI.





discovery of cells discovery of microorganisms

Robert Hooke (1635-1703) – compound microscopes, 30x Antoni van Leeuwenhoek (1632-1723) – single-lens microscopes, 250x

MICROGRAPHIA:

OR SOME

Physiological Descriptions

OF

MINUTE BODIES

MADE BY

MAGNIFYING GLASSES.

WITH

OBSERVATIONS and INQUIRIES thereupon.

By R. HOOKE, Fellow of the ROYAL SOCIETY.

Non possis oculo quantum contendere Linceus, Non tamen idcirco contemnas Lippus inungi. Horat. Ep. lib. 1.



LONDON, Printed by Jo. Martyn, and Ja. Allestry, Printers to the ROYAL SOCIETY, and are to be fold at their Shop at the Bell in S. Paul's Church-yard. M DC LX V.

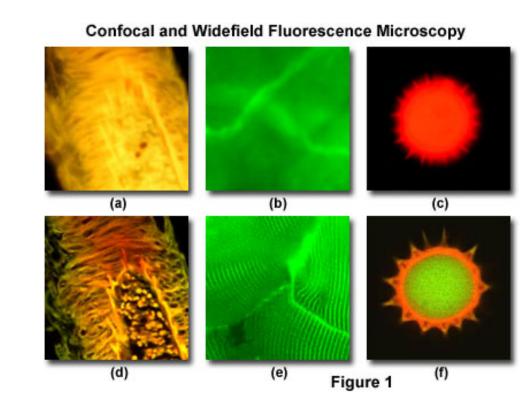
Optical microscope

Confocal microscope



Zeiss 1914





Excitation source: laser

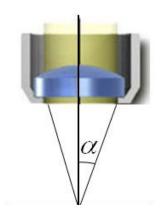
Advanced optical system that selects only the part of the sample that is on focus (field depth) + successive images (optical sections)

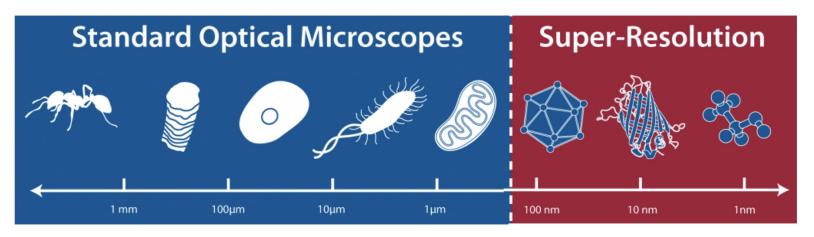
Fluorescence version (staining with fluorescent dyes)

Abbe's Diffraction Limit:

→ resolution limit

$$\Delta x \cong \frac{\lambda}{2n\sin\alpha}$$





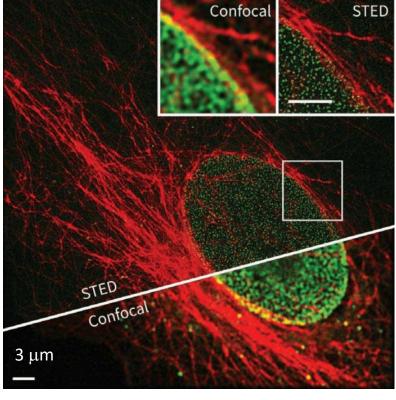
Abbe's Equation Modified for Fluorescence:

$$\Delta x \cong \frac{\lambda}{2n \sin \alpha \sqrt{1 + \zeta}} \qquad \begin{bmatrix} \zeta \to 0 & \text{Abbe Limit} \\ \zeta \to \infty & \Delta x \to 0 \end{bmatrix}$$
 Saturation Factor $\zeta = I(x)/I_{sat}$



Stefan Hell STED

Eric Betzig William E. Moerner PALM



Wave nature of electrons



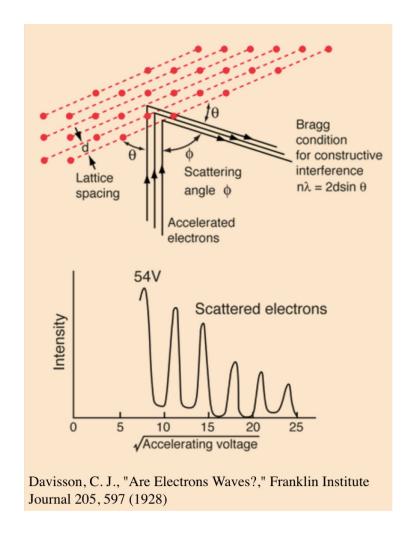
$$\lambda = \frac{h}{p} = \frac{h}{\sqrt{2mE}}$$

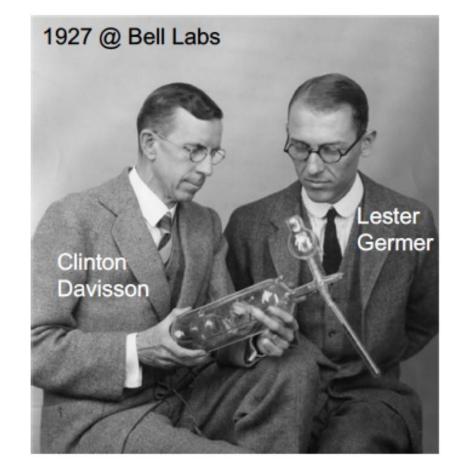
wave-particle duality de Broglie wavelength (1924)

diffraction peaks observed

$$E = 54 \text{ eV}$$

 $\lambda = 0.17 \text{ nm}$



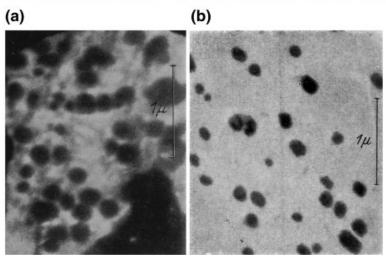


Transmission Electron Microscope (TEM)





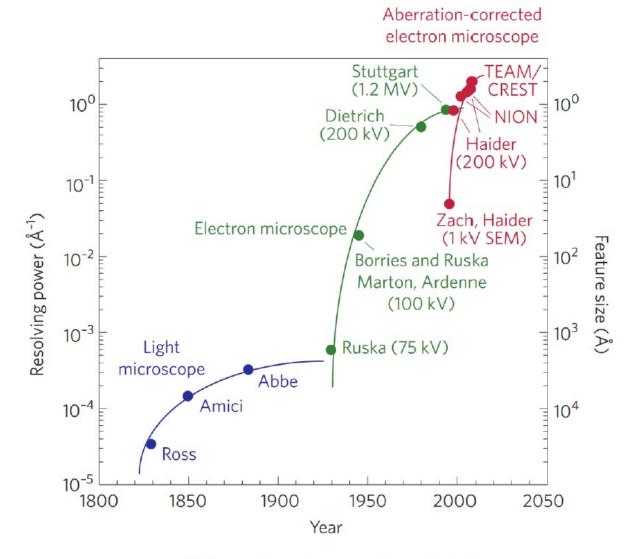


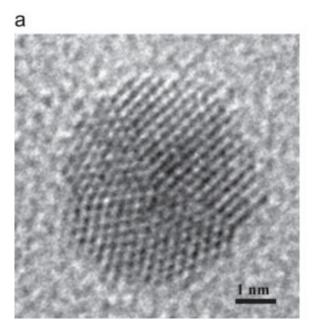


1933 Ernst Ruska

Transmission Electron Microscope (TEM)

energies in the range 50 keV to 400 keV





Au nanoparticle

Progr. Nat. Sci.: Mat. Inter. 23, 222 (2013)

DUBOCHET'S VITRIFICATION METHOD

transferred to a metal mesh and excess material removed. 7 The sample forms a thin mesh when it is shot into ethane at about -190°C. The water vitrifies around the sample. ETHANE which then is cooled by liquid nitrogen during the measurements in the electron microscope. -196° LIQUID **NITROGEN**

Cryo TEM

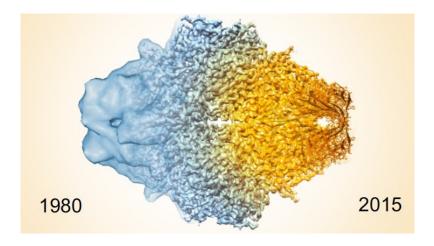


Jacques Dubochet
Joachim Frank

Richard Henderson

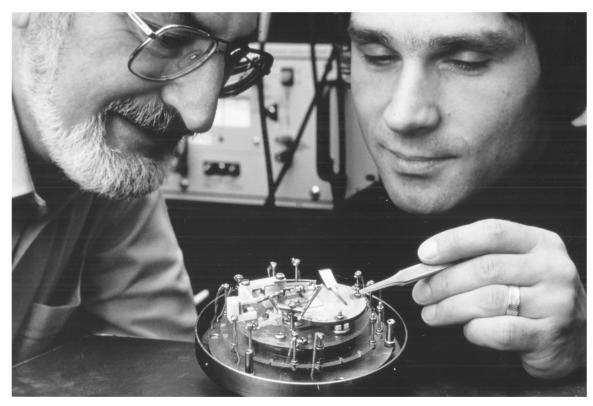
biological samples are not compatible with UHV: water desorbs and the sample is destroyed by the TEM e-beam

vitrification: rapid cooling of the sample, no water cristallization, but vitreus matrix that protects the biological samples



Scanning Tunneling Microscope (STM)





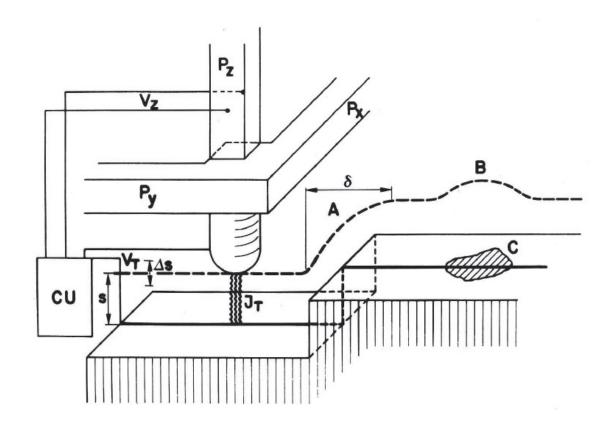
Heinrich Rohrer

Gerd Binnig

IBM Rüschlikon, 1981

Phys. Rev. Lett 50, 120 (1983)

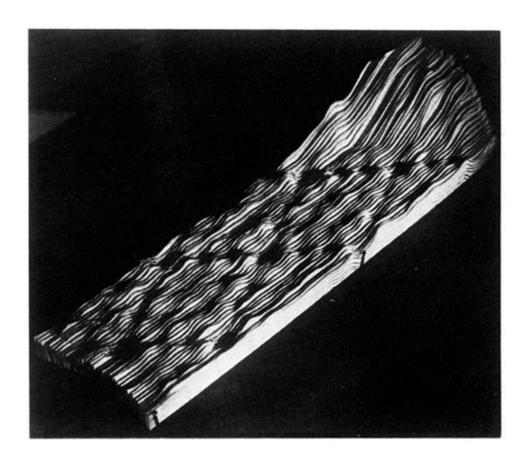
Helv. Phys. Acta **55**, 726 (1982)

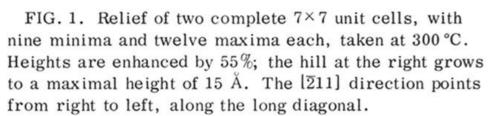


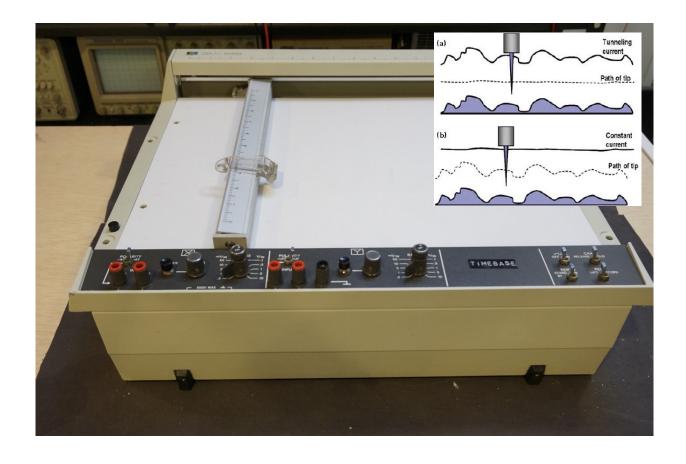
based on quantum tunneling effect

typical currents: < 1 nA

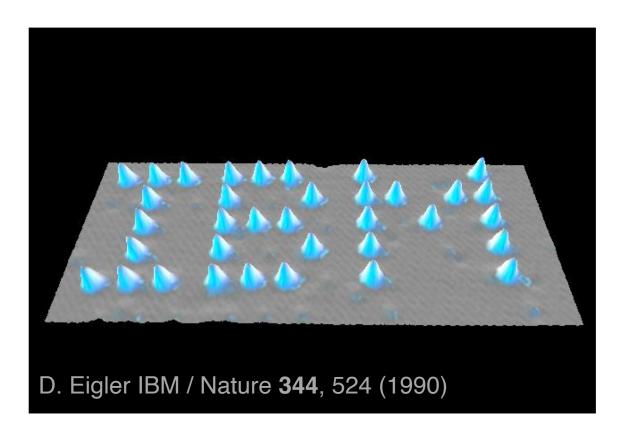
Scanning Tunneling Microscope (STM)







Scanning Tunneling Microscope (STM)



a powerful tool:

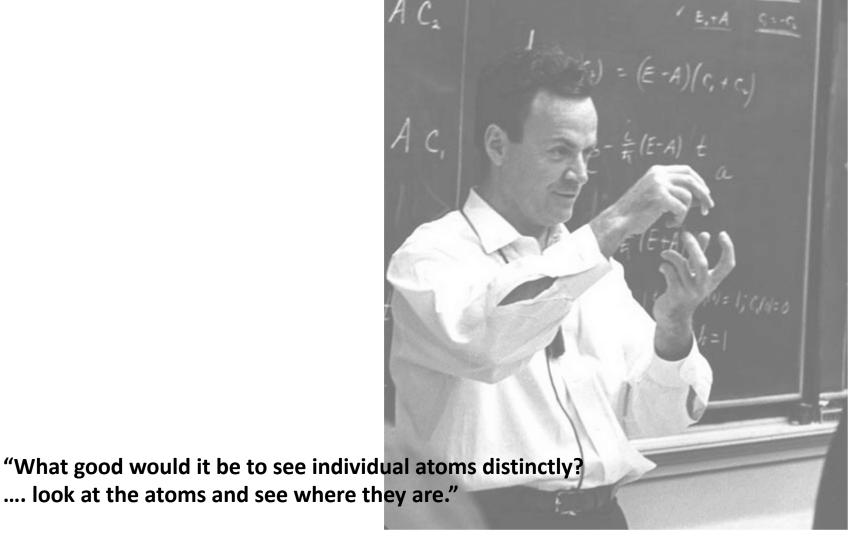
- imaging of surfaces and supported nanostructures
- manipulation at atomic level
- spectroscopy

for high-end applications, requirements:

- UHV
- low noise
- low vibrations
- low temperature

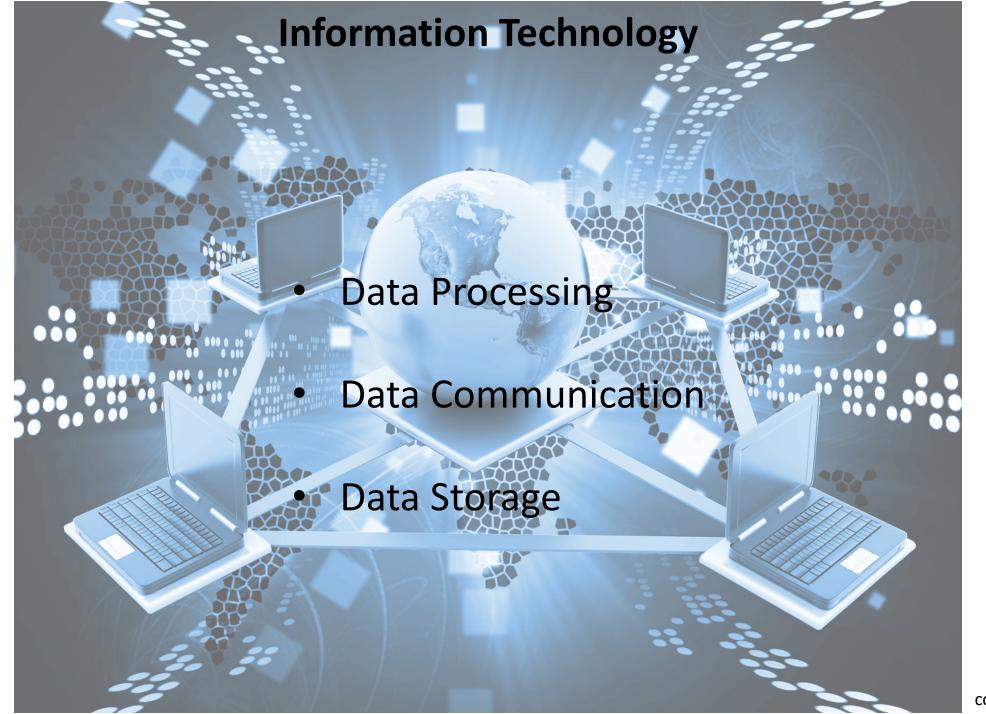
There's plenty of room at the bottom (1959)



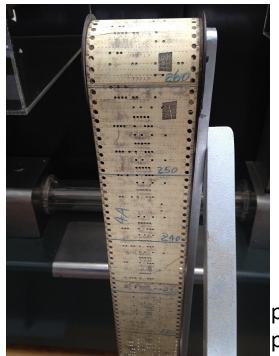


"But I am not afraid to consider the final question as to whether, ultimately – in the great future – we can arrange the atoms the way we want; the very atoms, all the way down!"

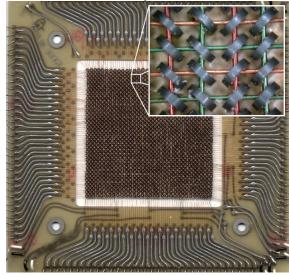
Richard Feynman



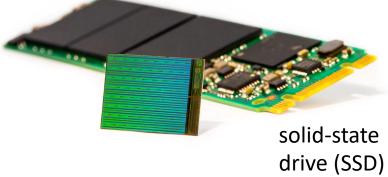
Data storage (historical, not exhaustive)



magnetic-core memory



Control Source Drain Floating Thin Oxide p substrate



punched tapes punched cards

(HDD)





digital data binary system

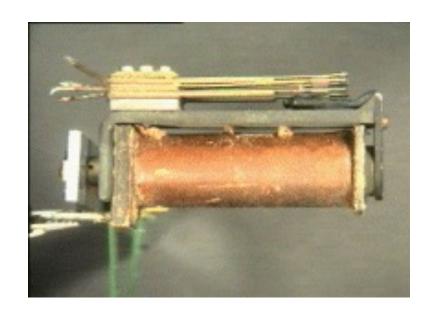
any number (or instruction) can be represented by a sequence of bits (binary digits) which are in turn represented by any mechanism capable of being in two mutually exclusive states (1 and 0)

Data processing

binary systems - switches

Boolean algebra

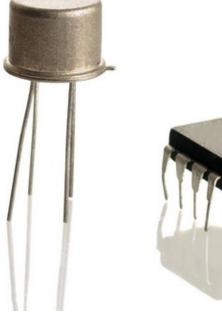
(logical operators, variables: true = 1, false =0)



http://zuse.zib.de/relay electromechanical relays 1930-1950



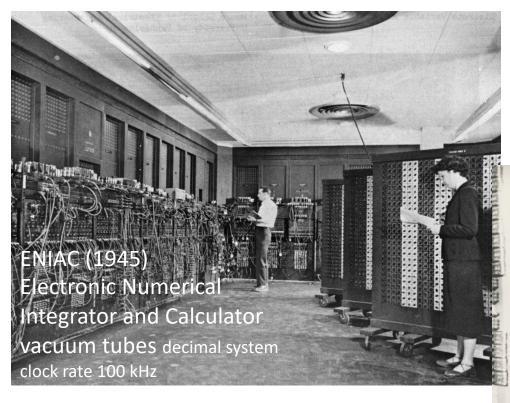
vacuum tubes – triodes 1940-1965



transistors from 1960

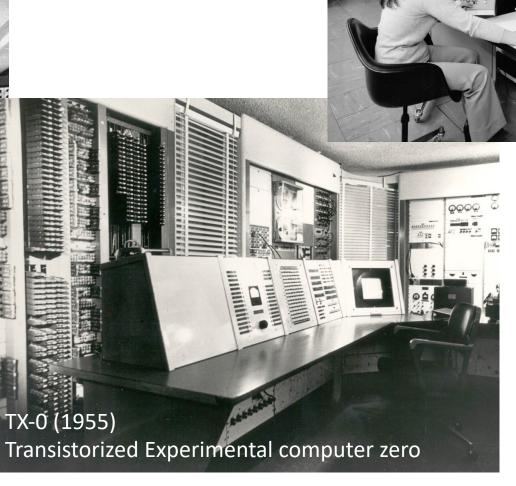


Zuse Z3 (1941) electromechanical relays binary system



EDVAC (1949) vacuum tubes binary





PDP-10 (1975)

Smartphones: a Supercomputer in your Pocket



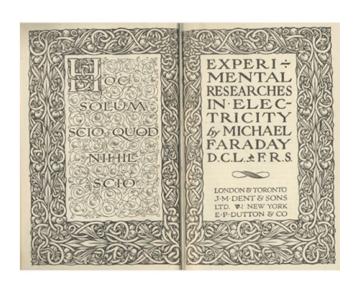


1984 2023

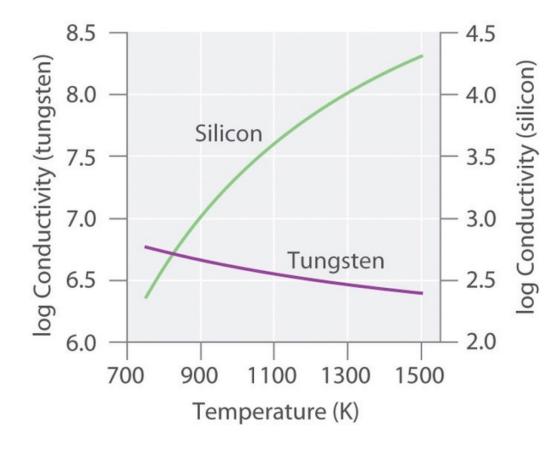
 10^7 \$ 10^3 \$

105 MHz CPU clock rate 3.46 GHz

Michael Faraday



Semiconductors



discovery of semiconductors (1833) (silver sulfide)



Semiconductors



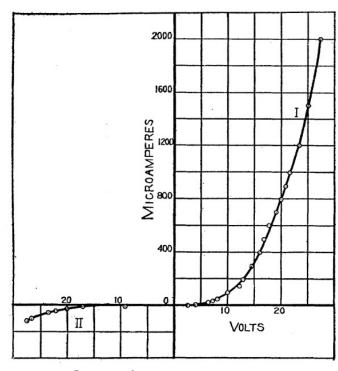
Karl Ferdinand Braun

Ann. der Physik und Chemie (1874) "Ueber die Stromleitung durch Schwefelmetalle"



lead sulfide (galena) wire contact (cat whisker)

unilateral conduction → crystal detector point-contact diode

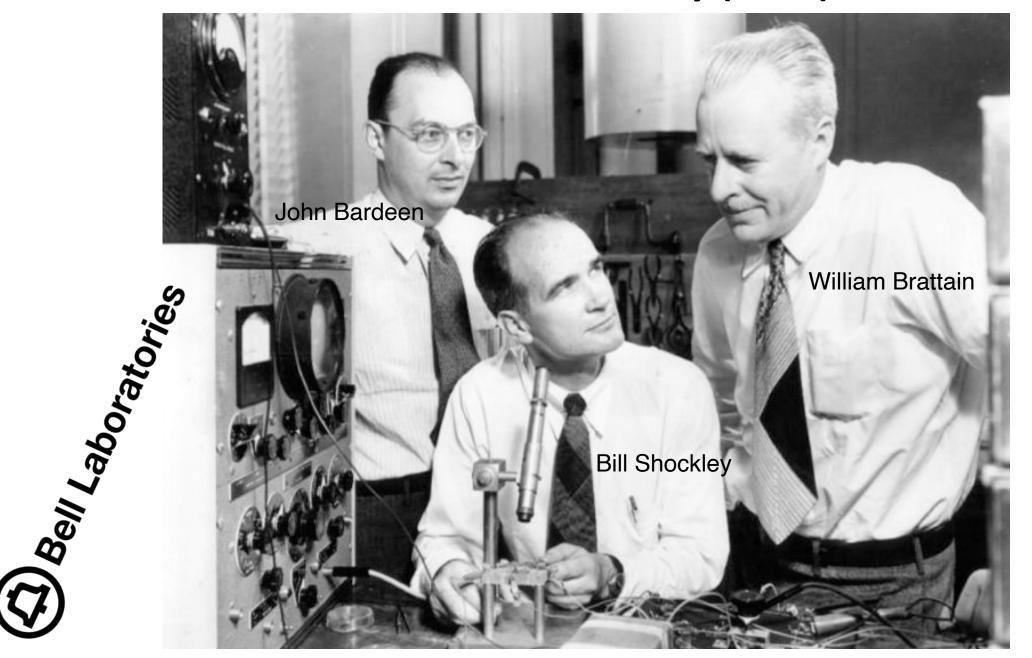


G.W. Pierce Phys. Rev. **5**, 31 (1907)

carborundum

Transistor discovery (1947)





Transistor discovery (1947)

Phys. Rev. **74**, 230 (1948)

The Transistor, A Semi-Conductor Triode

J. BARDEEN AND W. H. BRATTAIN

Bell Telephone Laboratories, Murray Hill, New Jersey

June 25, 1948

A THREE-ELEMENT electronic device which utilizes a newly discovered principle involving a semi-conductor as the basic element is described. It may be employed as an amplifier, oscillator, and for other purposes for which vacuum tubes are ordinarily used. The device consists of three electrodes placed on a block of germanium as shown schematically in Fig. 1. Two, called the emitter and collector, are of the point-contact rectifier type and are placed in close proximity (separation ~.005 to .025 cm) on the upper surface. The third is a large area low resistance contact on the base.

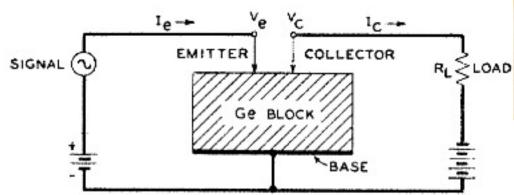
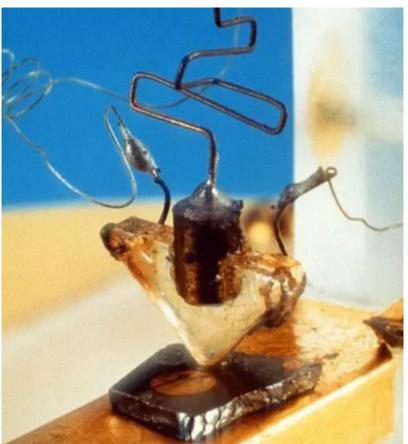
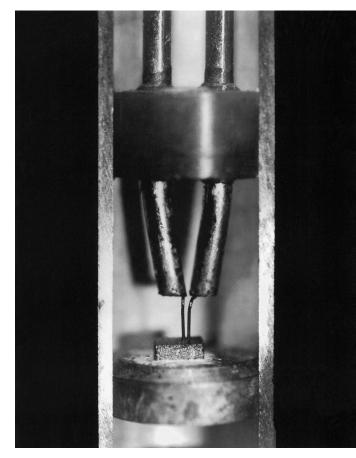


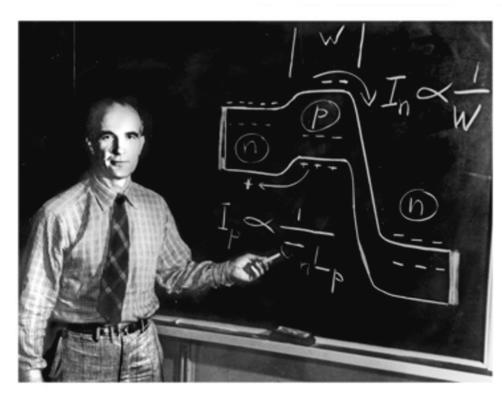
FIG. 1. Schematic of semi-conductor triode.



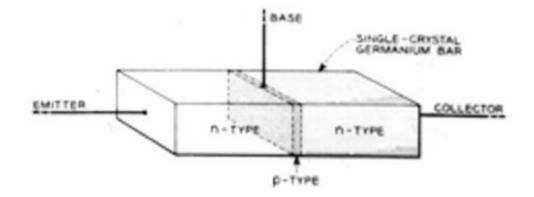
point contact transistor



Bipolar Junction Transistor (1948)



Bill Shockley



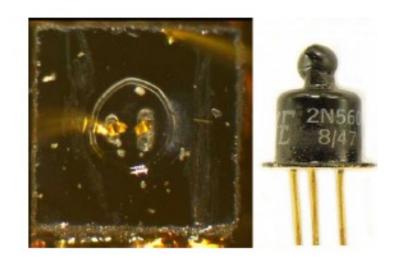


From germanium to silicon (mid 1950's)





Morris Tanenbaum, Bell Labs, 1954/55



Shockley Semiconductor Lab (1955)



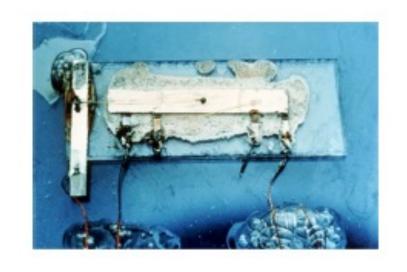


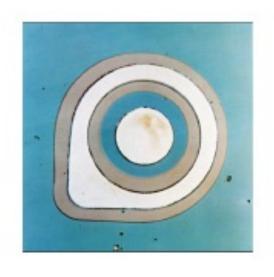
Fairchild Semiconductors (1957)





Going 2D







Jack Kilby

first all semiconductor solid circuit

(1958)

Jean Hoerni Fairchild

> first planar process

> > (1960)

Robert Noyce Fairchild

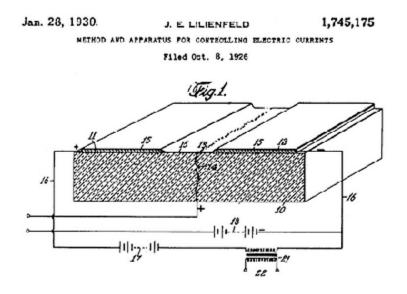
first planar

IC

(1960)

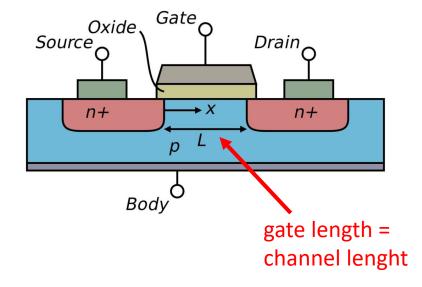
Thing Eagon Citienteur

J.E. Lilienfeld, Bell Labs
US Patent (1926)
Semiconductor Field Effect Device

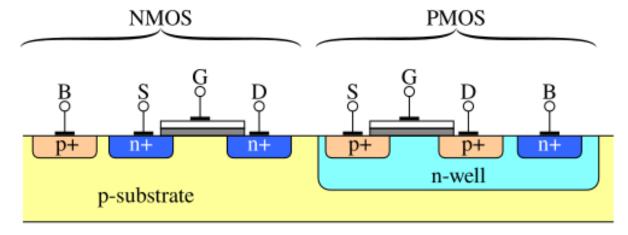


Field Effect Transistor

MOSFET (Metal-Oxide - Semiconductor FET) Bell Labs (1959)



CMOS (Complementary Metal-Oxide – Semiconductor) combining p-type and n-type MOSFETs for logic functions Fairchild Semiconductors (1963)



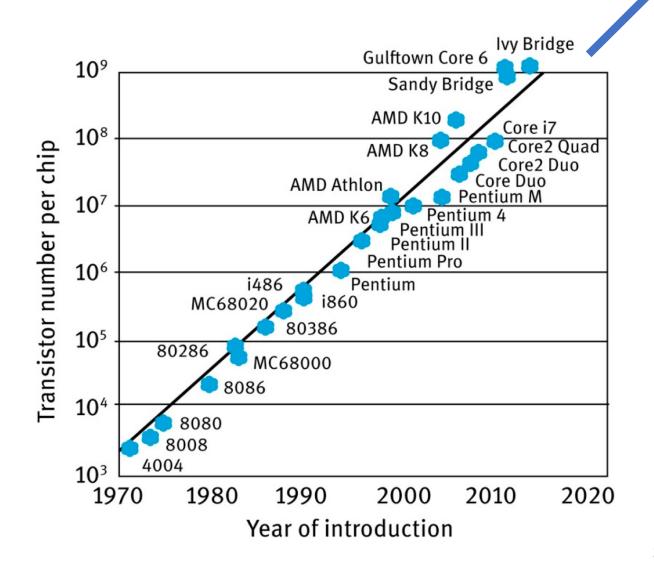
Miniaturization - Moore's law

Gordon E. Moore Co-founder, Intel Corporation.

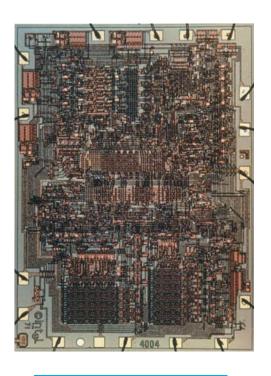
Electronics, Volume 38, Number 8 (1965)

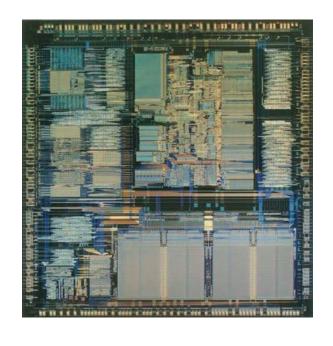
"With unit cost falling as the number of components per circuit rises, by 1975 economics may dictate squeezing as many as 65,000 components on a single silicon chip."

"The number of transistors on a piece of silicon will double every couple of years."



Miniaturization









1971 Intel® 4004 processor

Initial clock speed: 108KHz

Transistors: 2,300

Manufacturing technology: 10 micron

1985 Intel386™ processor

Initial clock speed: 16MHz

Transistors: 275,000

Manufacturing technology: 1.5 micron

2000 Intel® Pentium® 4 processor

Initial clock speed: 1.5GHz

Transistors: 42 million

Manufacturing technology: 0.18 micron

2012 3rd generation Intel® Core™ processor

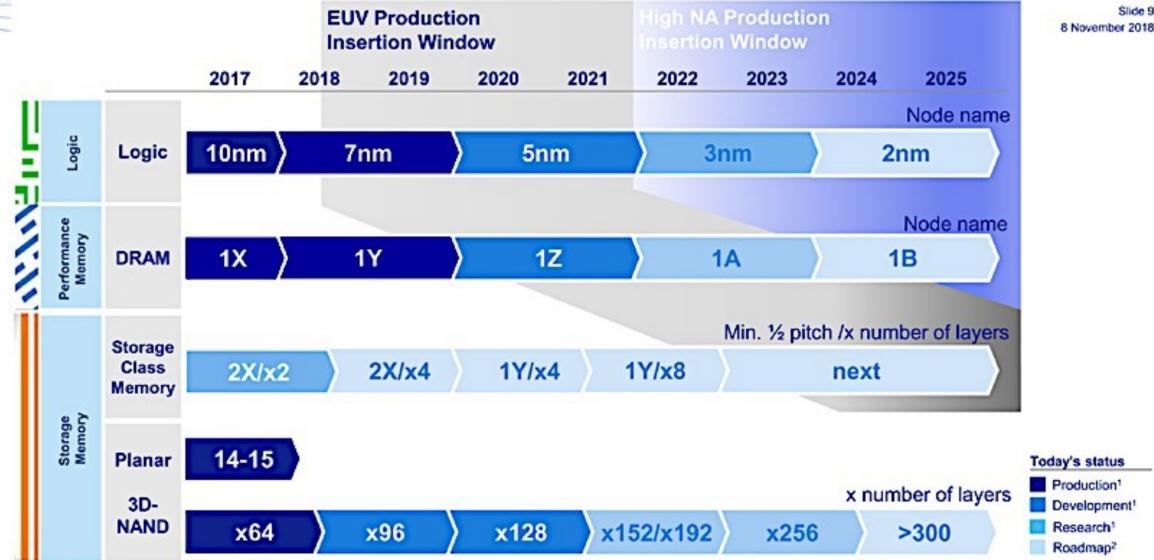
Initial clock speed: 2.9GHz

Transistors: 1.4 billion

Manufacturing technology: 22nm

Customers' scaling roadmaps continue

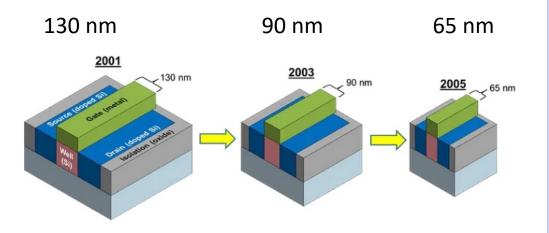




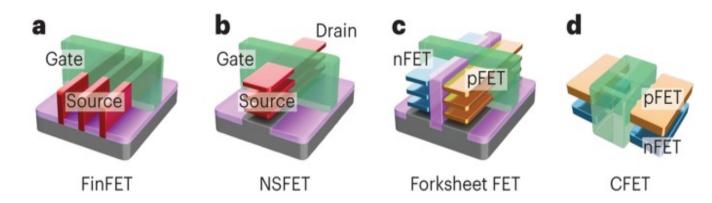
FET fabrication technology roadmaps - Nodes

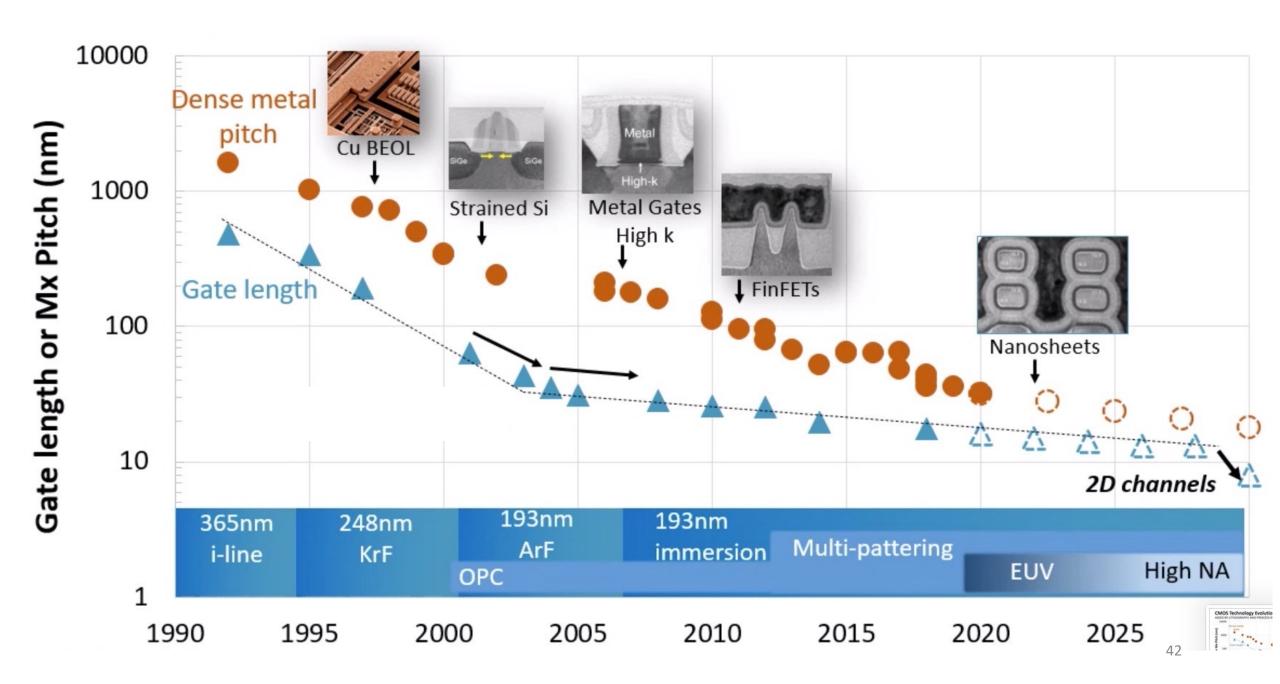
in early days until 2008
MOSFETs were purely planar, the node name
(technology or process node) corresponds
the size of the smalles feature on a processor,
usually the gate length

50 μm mid 1960's 1 μm late 1960's 350 nm late 1990's



after 2008
transistors go in the third dimension;
the node name is not anymore related to feature sizes; it rather indicates the **transistor density**other ways to optimize the density (packing, stacking in third dimension...)



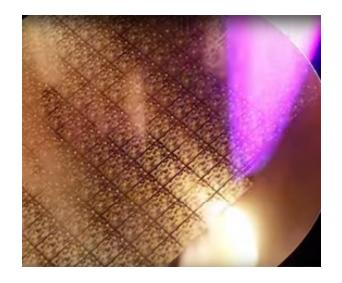


Integrated Circuit Fabrication

thin film deposition CVD, PVD, ALD

lithography (today 13.5 nm Extreme UV litography)

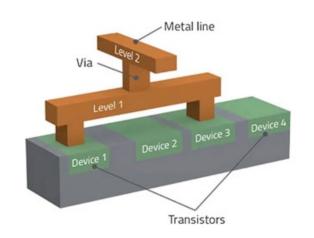
etching

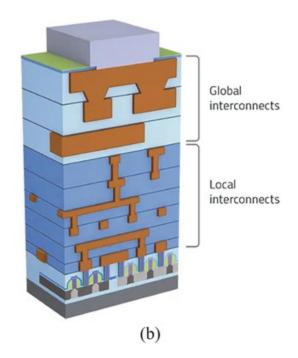


doping

cleaning

requires tens or even hundreds of successive steps

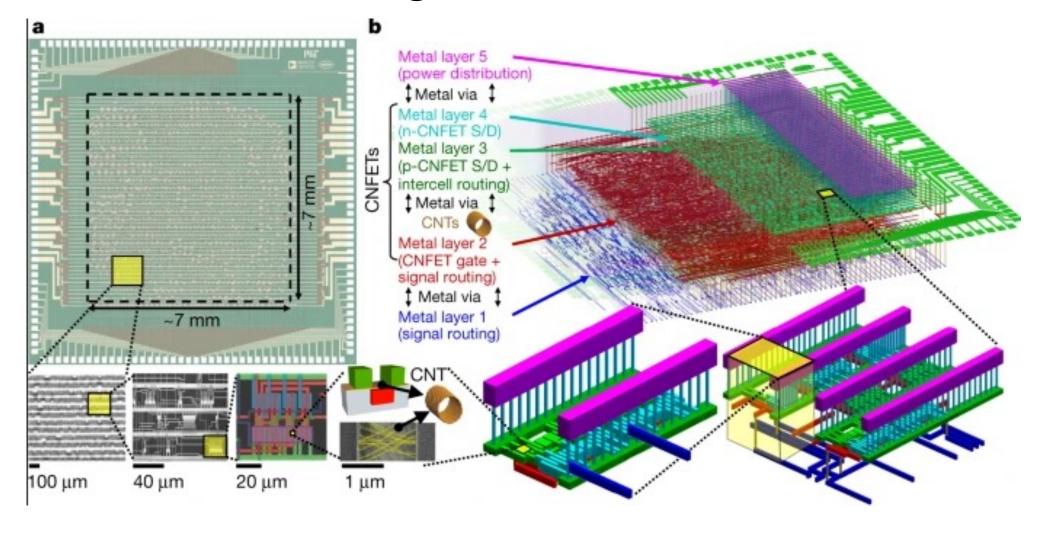




Carbon-based digital electronics

graphene or carbon nanotubes as channel materials

other 2D materials (MoS₂, ...)



Modern microprocessor built from complementary carbon nanotube transistors, Nature **572**, 595 (2019)

14'000 transistor computer – Turing complete